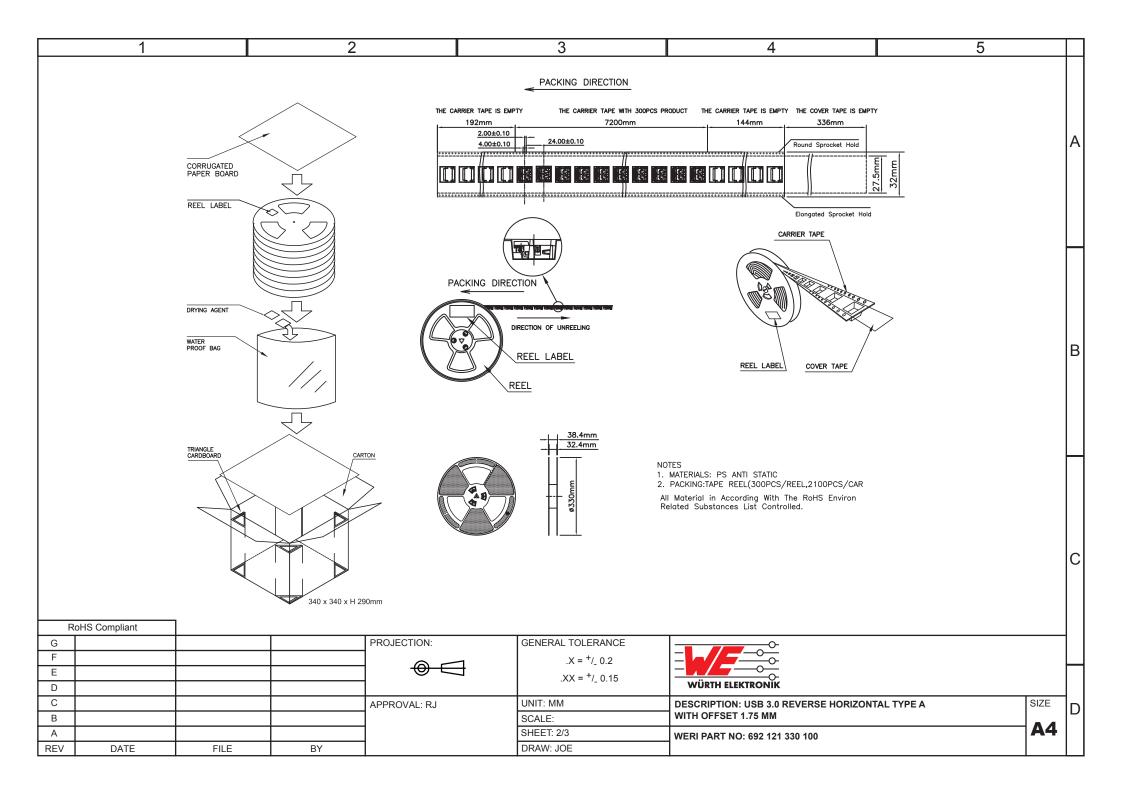
	1		2		3	4	5		Ţ
						SOLDEI SHIELDING: BRASS MATT TIN	/0 HORE BRONZE PLATE 1.27 to 2.54 µm Ni CT AREA 0.76 µm Gold R TAIL AREA 2.54 to 5.08 µm Matt Tir	١	A
				×.	15.70 15.70 15.70 0.66 0.66 0.66 0.66 0.66 0.80 0.80 0.80		FREE AS PER DIRECTIVE 2002/95/I EE COMPLIANT AS PER IEC 61249-2 bonding ground PIN) 1.8A Max VOLTAGE: 100Vac/min 100MΩ		E
Ro	HS Compliant		2x1.00 2x2.00 2x3.50 2x4.00		2.00 4.00 4.00 13.50 15.30 AYOUT * - COMPONENT VIEW <sup>1</sup>	MECHANICAL INSERTION FORCE: 35.0N Ma EXTRACTION FORCE: 10.0N MA QUALITY CLASS: 5000 MATIN SOLDERING WAVE PROCESS AS PER JED PACKAGING TAPE & REEL	nin G CYCLES DEC J-STD-020D	<del>R</del> Υ ΤΟ	C
G F E	01-APR-14 12-AUG-13 09-NOV-11	SOLDERING DWG & CHARAC STENCIL	QL QL GG		GENERAL TOLERANCE $.X = \frac{+}{.} 0.2$				
D	21-SEP-11	NOTE	GG		.XX = <sup>+</sup> /_ 0.15				
С	10-MAY-11	UL	GG	APPROVAL: RJ	UNIT: MM	DESCRIPTION: USB 3.0 REVERSE HORIZO	NTAL TYPE A	SIZE	٦
В	02-MAY-11	DIMENSION	GG		SCALE:	WITH OFFSET 1.75 MM			_ I *
А	04-AUG-10	PDF	JP		SHEET: 1/3	WERI PART NO: 692 121 330 100		<b>A4</b>	
REV	DATE	FILE	BY		DRAW: JOE				



1	2	3	4	5	
Stencil information for T	hrough Hole Reflow soldering		PCB cross section		
			Hole Volume		
				Pin Volume	
9 0 0			Free volume for Theoritical Formula for Through Hole	e pins	В
			Volume of the stencil aperture = (Ho or Volume of solder paste = (Hole volu		
STENCIL	LAYOUT * - COMPONENT VIEW		Stencil Stencil Thickness: 150 µm		
			PCB PCB thickness: 1.6mm		С
RoHS Compliant * NOTE: SEE	PCB LAYOUT PAGE 1/3 FOR MISSING DIMENSIONS				
G F E D		GENERAL TOLERANCE .X = <sup>+</sup> /_ 0.2 .XX = <sup>+</sup> /_ 0.15			┝
C B	APPROVAL: RJ	UNIT: MM SCALE:	DESCRIPTION: USB 3.0 REVERSE HORIZON WITH OFFSET 1.75 MM	SIZE	יין
A   REV DATE   FILE	BY	SHEET: 3/3 DRAW: JOE	WERI PART NO: 692 121 330 100		